



TOHOKU  
UNIVERSITY

## Workshop on Advanced Superconducting Materials and Magnets

KEK Tsukuba Campus., Jan. 21-23, 2019

# Design concept and R&D studies for upgrading of 25T cryogen-free superconducting magnet

Satoshi Awaji

High Field Laboratory for Superconducting Materials,  
IMR, Tohoku University





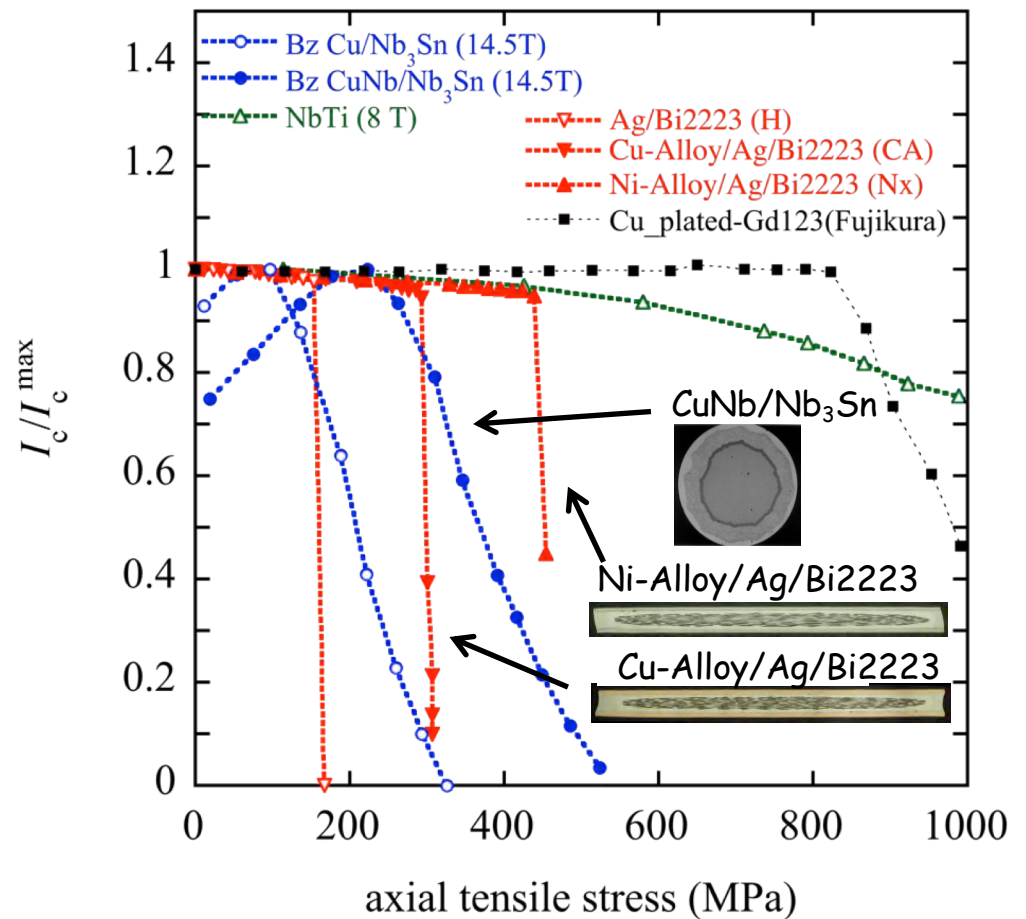
TOHOKU  
UNIVERSITY

# Acknowledgements to collaborators

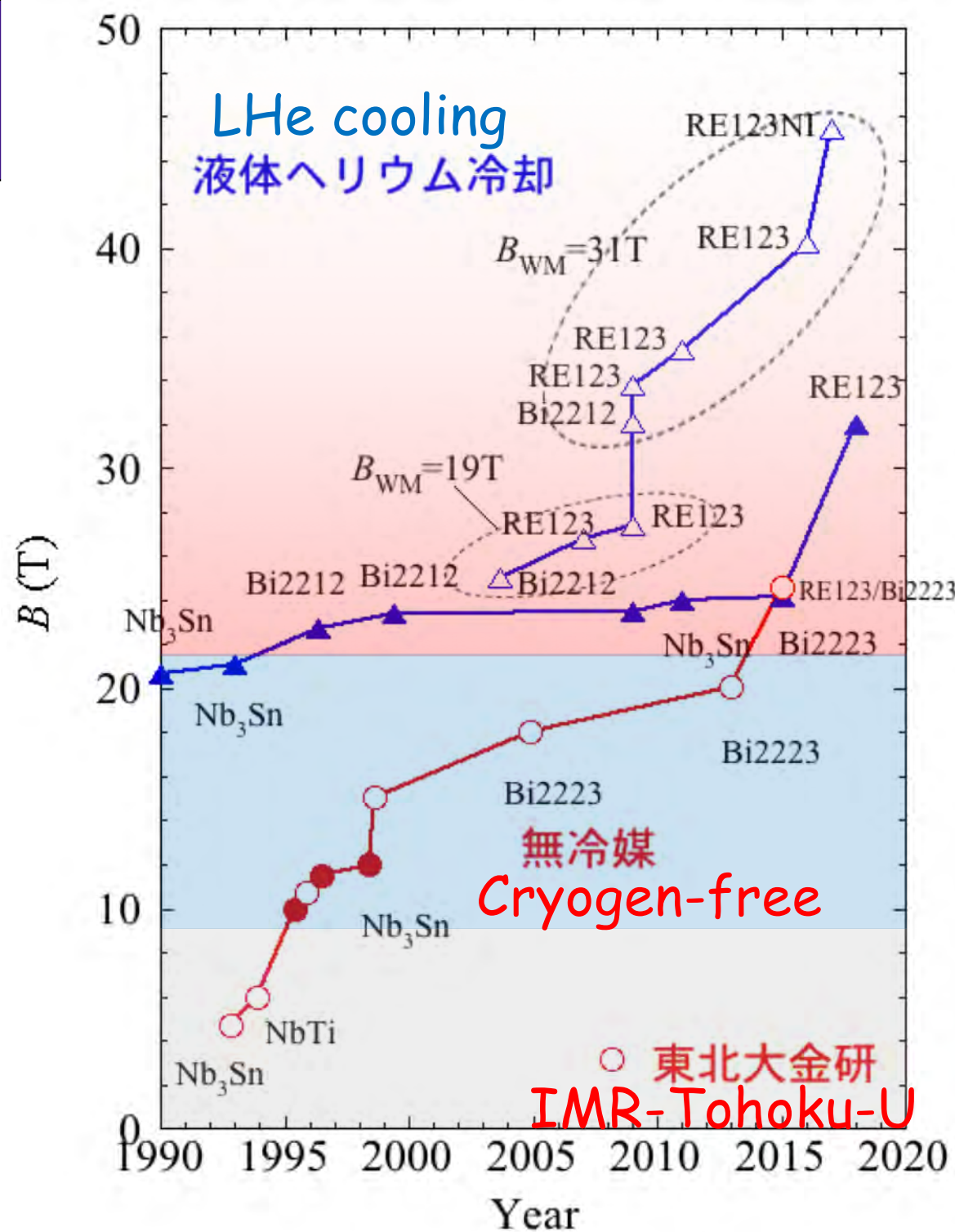
HFLSM, IMR, Tohoku Univ.  
Toshiba (Magnet system)  
Fujikura (Gd123 tapes)  
Furukawa (LTS cables)  
NIMS(R&D)  
Kyusyu-U (AC-loss)

T. Okada, K. Takahashi, A. Badel  
H. Miyazaki, S. Hanai, S. Ioka  
S. Fujita, H. Iijima, M. Daibo  
M. Sugimoto, H. Tsubouchi  
G. Nishijima,  
K. Kajikawa

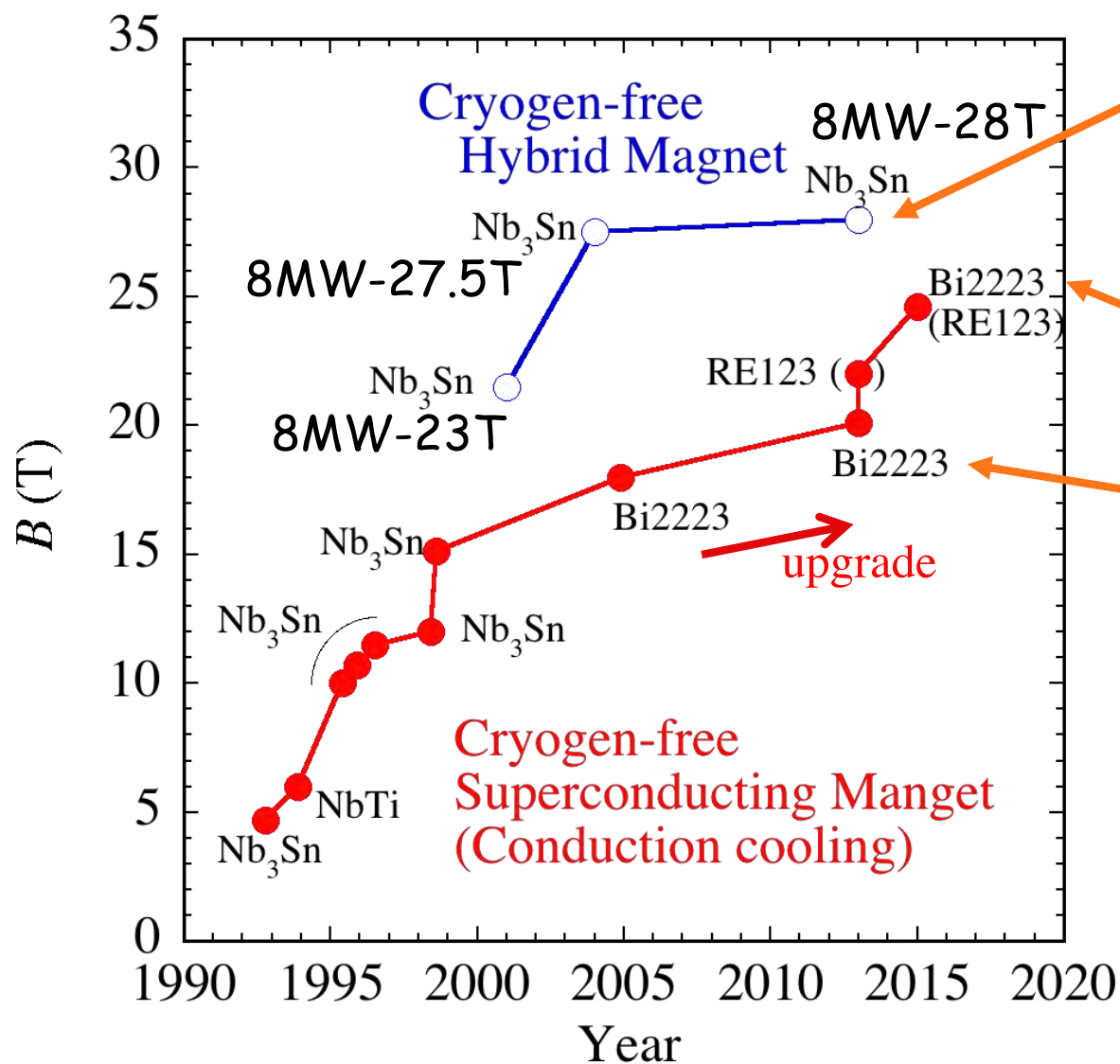




# Present status of HF magnets







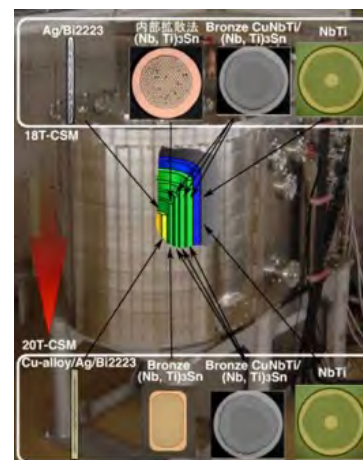
28T-CHM ( $\phi 32$ RT)



$\phi 360$ -9T-CSM  
+  $\phi 32$ -19T-WM

20T-CSM( $\phi 52$ RT)

25T-CSM( $\phi 52$ RT)



Bi2223

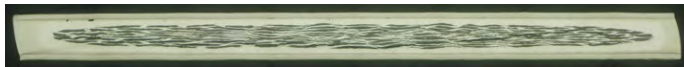


Gd123, Bi2223

# 25T Cryogen-free Superconducting Magnet (25T-CSM)

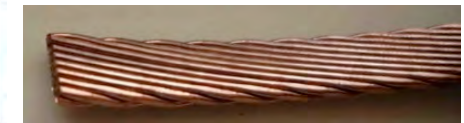
**Magnets (HTS): 10.6T@188A**

38 Ni-alloy/Bi2223 double pancakes  
 $\phi 96\text{ mm} \times \phi 280\text{ mm} \times h 390\text{ mm}$   
 Max. hoop stress 323 MPa



**Magnets (LTS): 14T@854A**

3 CuNb/Nb3Sn Rutherford solenoids  
 $\phi 300\text{ mm} \times \phi 539\text{ mm} \times h 628\text{ mm}$   
 Max. hoop stress 251 MPa



3 NbTi Rutherford solenoids  
 $\phi 545\text{ mm} \times \phi 712\text{ mm} \times h 628\text{ mm}$   
 Max. hoop stress 138 MPa

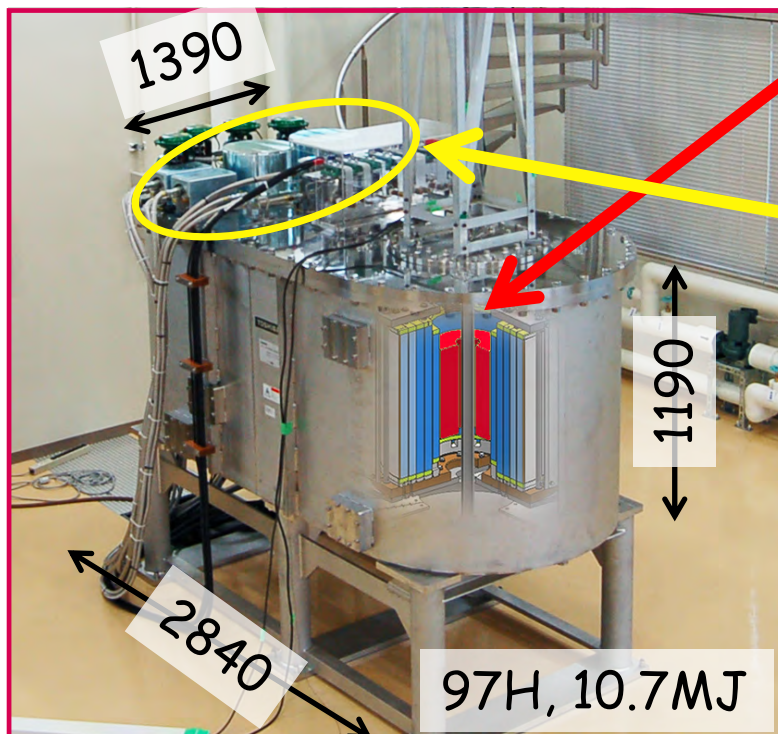
## Cooling system

Conduction cooling using He circulation

Shield: 2 x 1 stg GM cryocooler

**HTS: 2 x 4K-GM cryocooler**  
**(3W@4.2K, 10W@8K)**

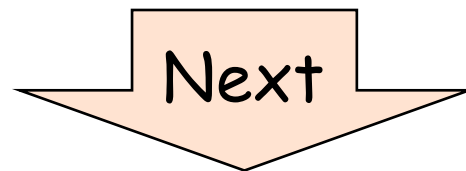
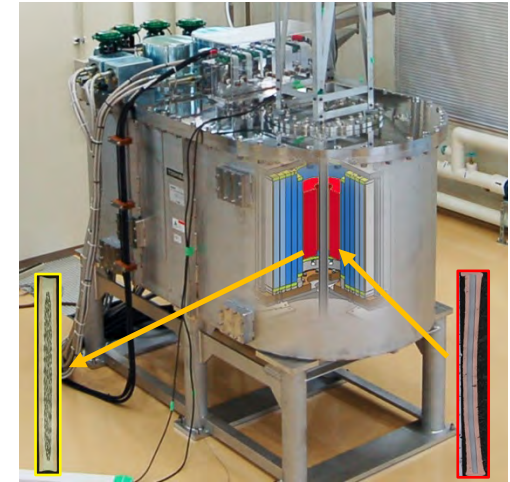
**LTS: 2 x GM/JT cryocooler (8.6W@4.3K)**



# Scenario beyond 30T-CSM

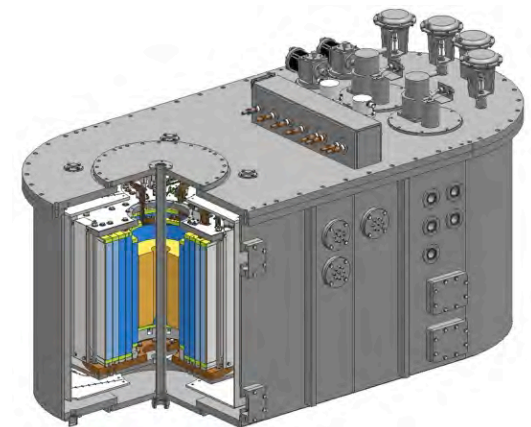
Upgrade of 25T-CSM replacing Bi2223 to REBCO insert (3-4 years) to 30T-CSM

- Low cost but many limited factors
  - Small margin (expect improvement of REBCO tapes)
- > Artificial pinning centers



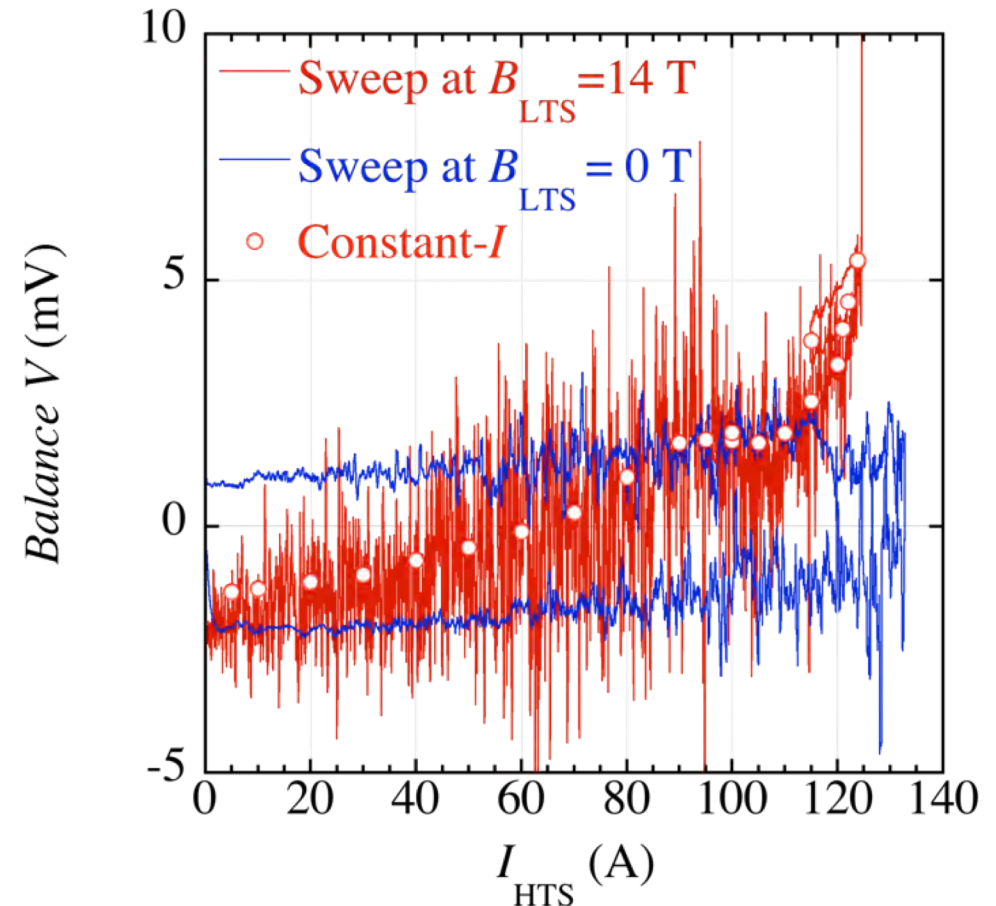
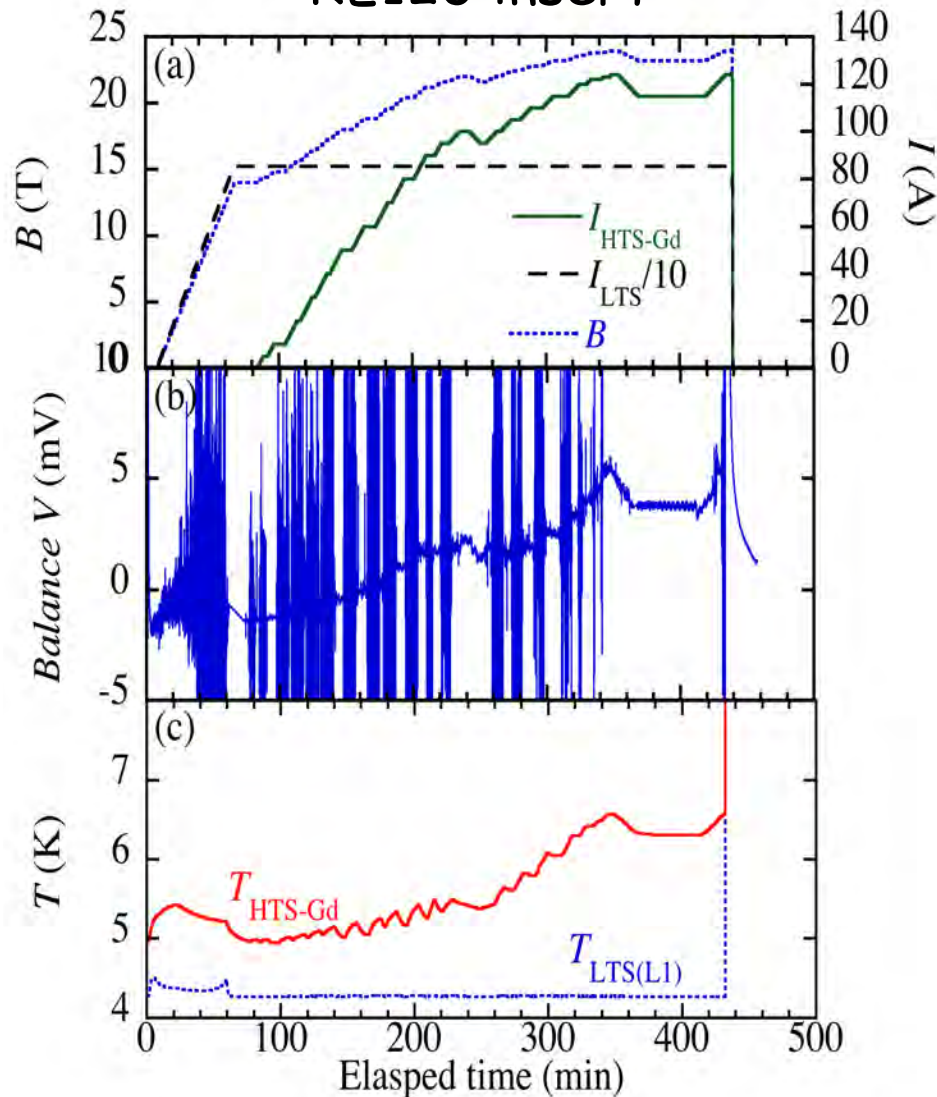
Beyond 30T-CSM (3-4 years)

- Consideration of 40 T in design
- > Improvement of mechanical strength of  $\text{Nb}_3\text{Sn}$  conductors are needed as well





## RE123 insert



The quench data was obtained!

Quench at  $B_{\text{cal}} = 24.01$  T (124.6 A)

Awaji *et al.*, SuST. 30 (2017) 065001



# Toward 30T-CSM

- REBCO is only solution, because of its high strength (800MPa). More high strength of Bi2223 tape is expected.
- Reliability of REBCO tapes
  - Improve **reliability** against local degradation.  
-> Current sharing with bundled tapes
- Quench protection
  - Against **local degradation** (REBCO)  
-> Dumping before burn-out with mV-scale detection.
  - Against quench of LTS coil  
-> Conventional dump resistance can be used.
- Mechanical reinforcement
  - 500 MPa for 30 T

# Strategy of upgrading design

- ✓ The additional high strength tapes are co-wound as the reinforcement to introduce a compressive radial stress in order to reduce a risk of degradation. An adequate tension would be added only in the reinforced tape if possible.
  - Reduce a risk of degradation
- ✓ More than two tapes are co-wound without an insulation in between the co-wound two tapes to share a current if the local degradation would occur.
  - Improve reliability
- ✓ A quench detection with a few mV is considered to protect the coil from the hot-spot. The balance voltage is used for the quench detection with a bridge circuit.
  - Protection from hot-spot

# Primitive upgrading design of RE123 insert for 30T-CSM

	Case 1	Case 2	Case 3
Wire (mm)	RE123 w4.1 x t0.11 x 2		
Thickness of Hastelloy (mm)	0.05		
Thickness of Cu stabilizer (mm)	0.02 (circumference)		
RT bore (mm)	32		
Inner x Outer diameters (mm)	68.0 x 274.0		
Coil height (mm)	290.9		
No. of turns/pancake	339	288	250
No of pancakes	56		
Operation current (A)	229	271	312
Total No of turns	19000	16128	14000
$B_{max}$ (T)	30.2		
$B_{r\ max}$ (T)	5.7	5.7	5.7
Central field (T)	16.0		
Self inductance (H)	21.2	15.1	11.4
Insulator thickness (mm)	0.06		
Reinforced tape thickness (mm)	0	0.05	0.1
Hight of pancake coil (mm)	4.9		
Thickness of cooling plate (mm)	0.3		
Space current density (A/mm <sup>2</sup> )	157	157	157
Conductor current density (A/mm <sup>2</sup> )	255	245	238
Maximum hoop stress in conductor (2 x RE123 + Hastelloy) $BJR$ (MPa)	499.4	482.2	468.2
Maximum hoop strain (%)	0.36	0.31	0.28

single winding



two-ply co-winding



- Increase a packing factor
- Current share for a local degradation

30T design was achieved by...

- two REBCO tape co-wound
- reinforced by co-wound Hastelloy

under the limited condition.

( $I_{op} < 300A$  & size limit)

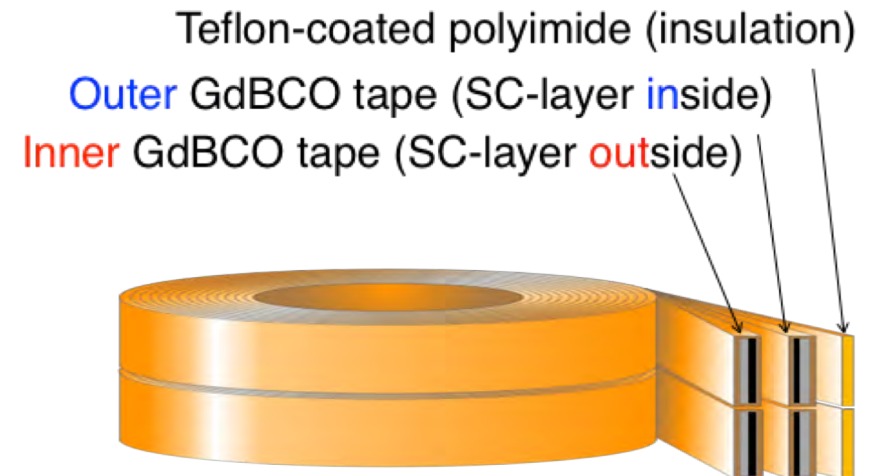
More improvement of design is under consideration!



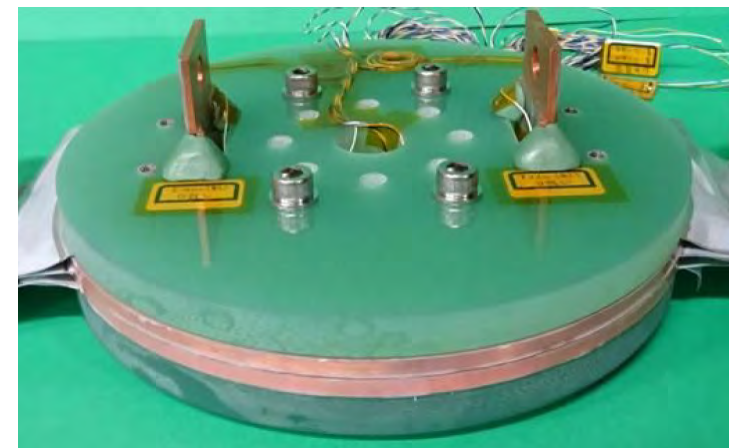
# Double pancake R&D coil

Tape	
Tape	RE123 tapes (Fujikura)
Tape width	4.1 mm
Tape thickness	0.13 mm
No of bundles tape	2
Thickness of Hastelloy Stabilizer	75 $\mu\text{m}$
	20 $\mu\text{m}$ electroplated Cu
Coil	
Inner diameter	100 mm
Outer diameter	168.5 mm
Coil height	100 mm
No. of turns/pancake	107
No of pancakes	2
Impregnation	Epoxy

$$L = 7.9\text{mH}$$



Epoxy impregnation



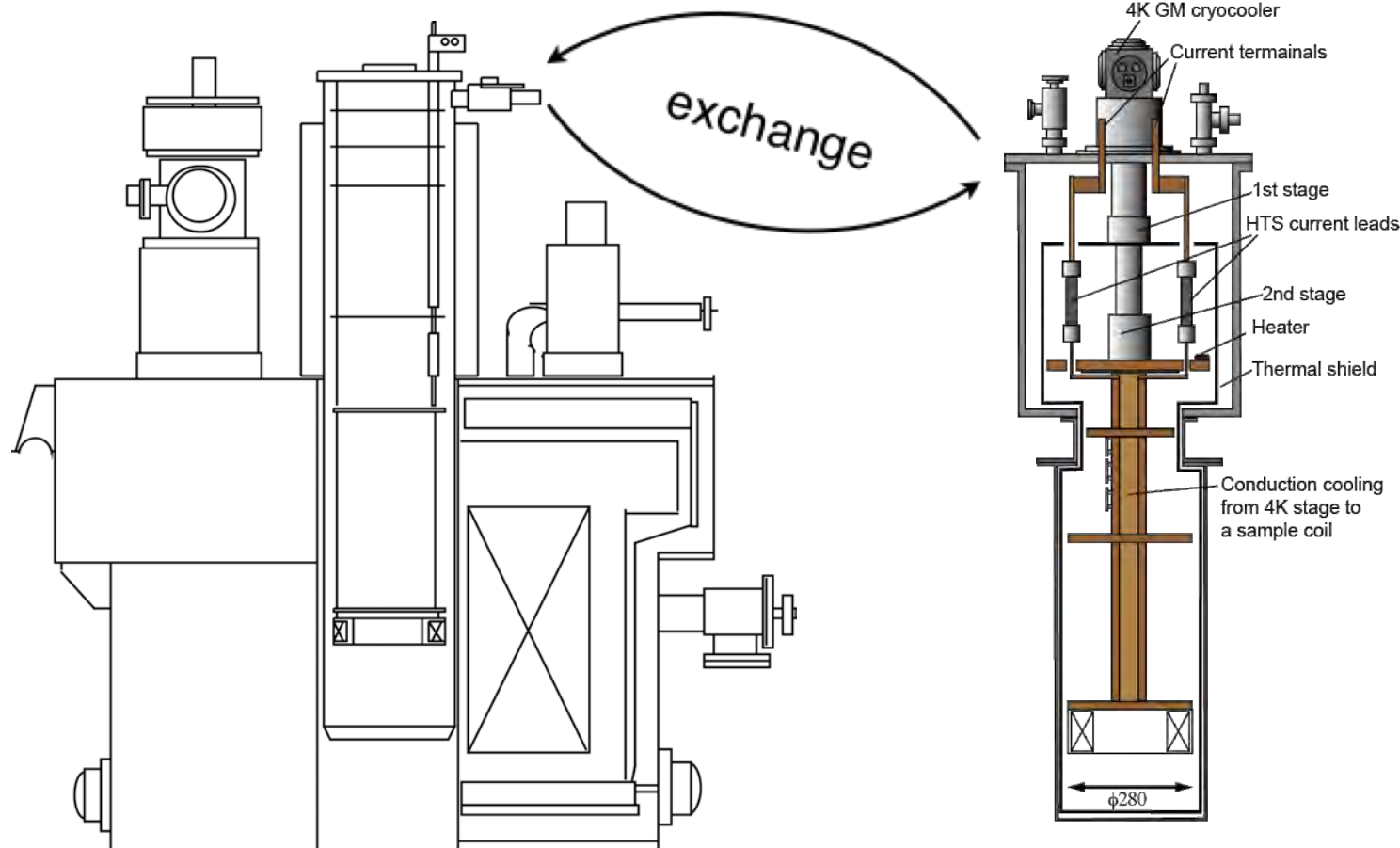
# Performance test of R&D coil under electromagnetic stress

## ①Hoop-stress test @4.2 K(LHe)

Large bore LHe  
Cryostat (<1500A)

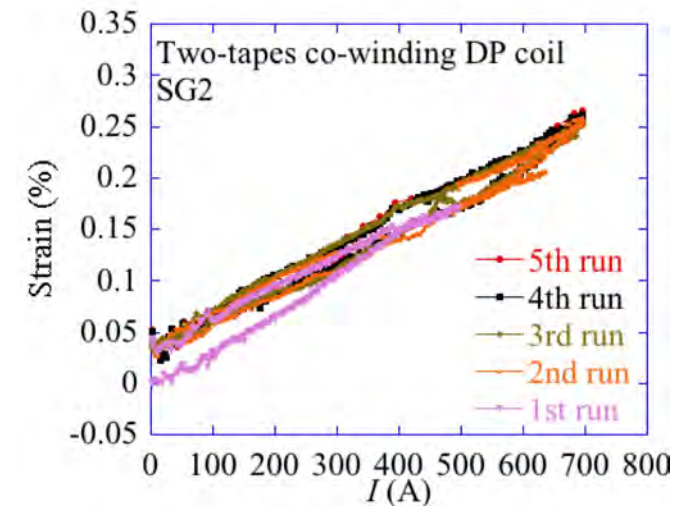
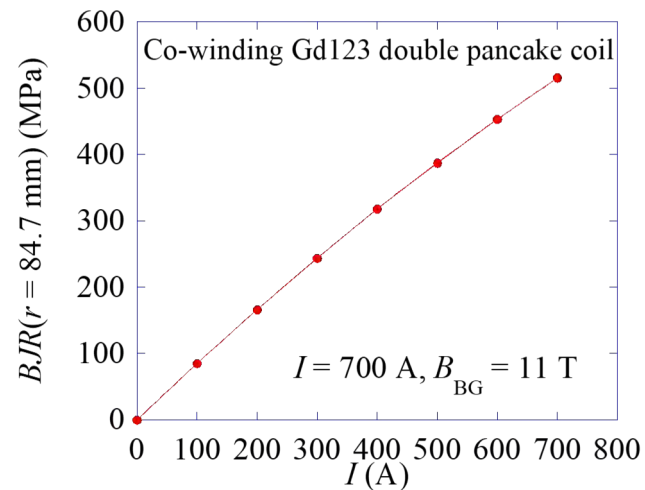
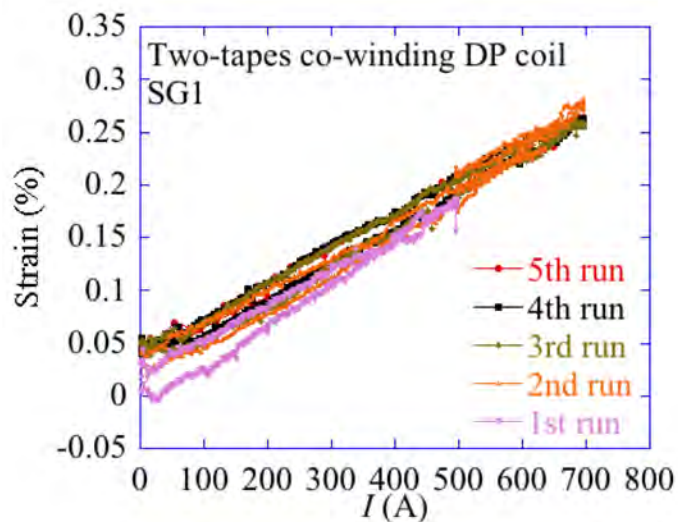
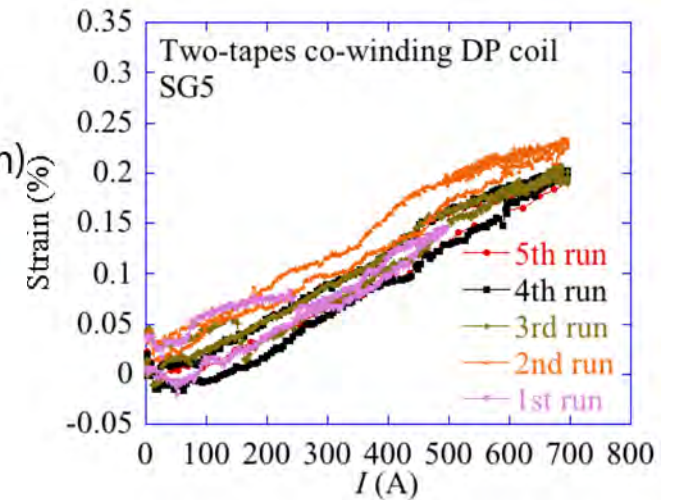
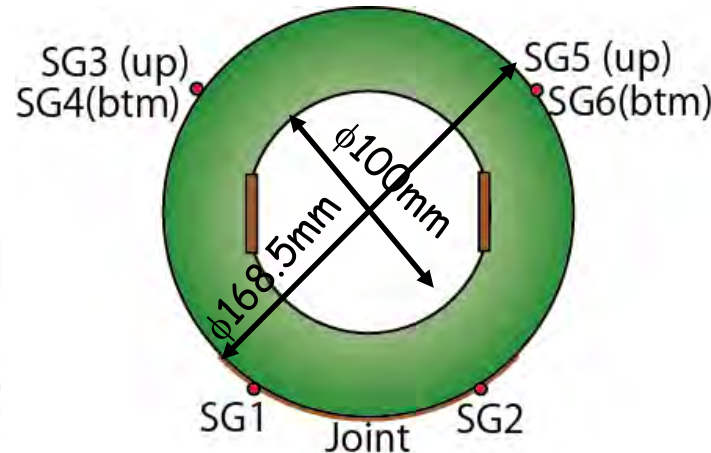
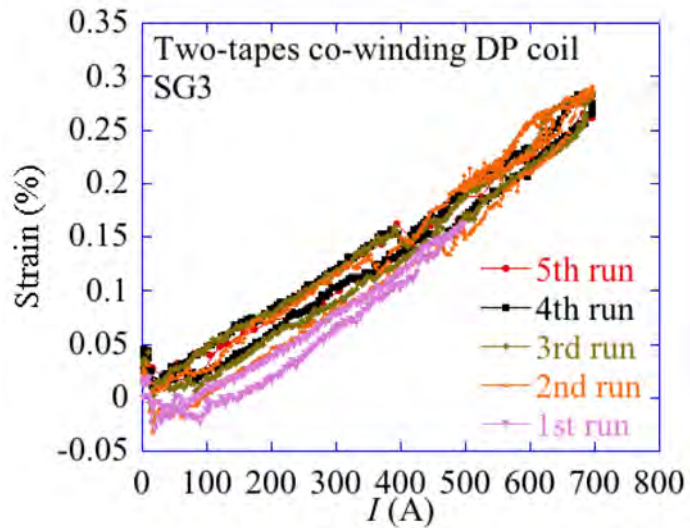
## ②Magnetic field measurement @10~30 K

Large bore Conduction-  
cooled Cryostat (<500A)



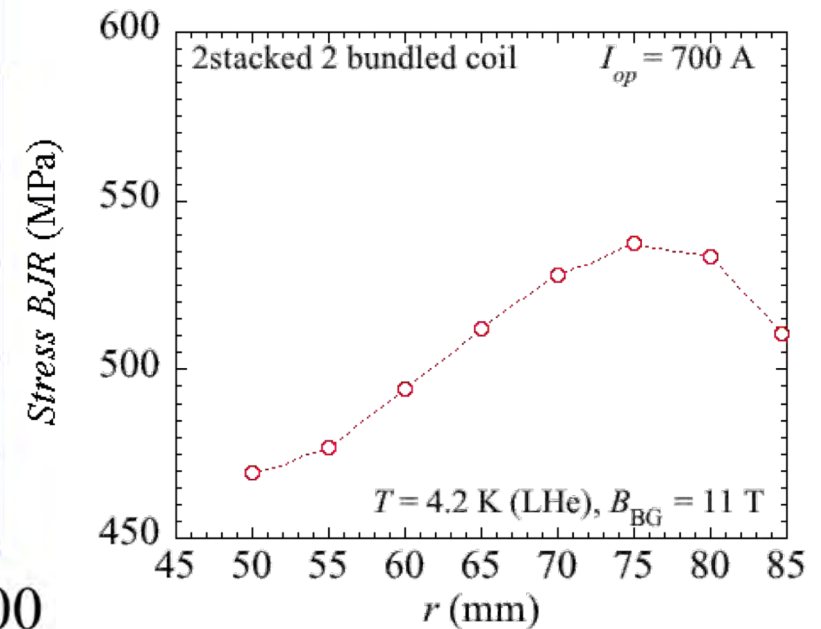
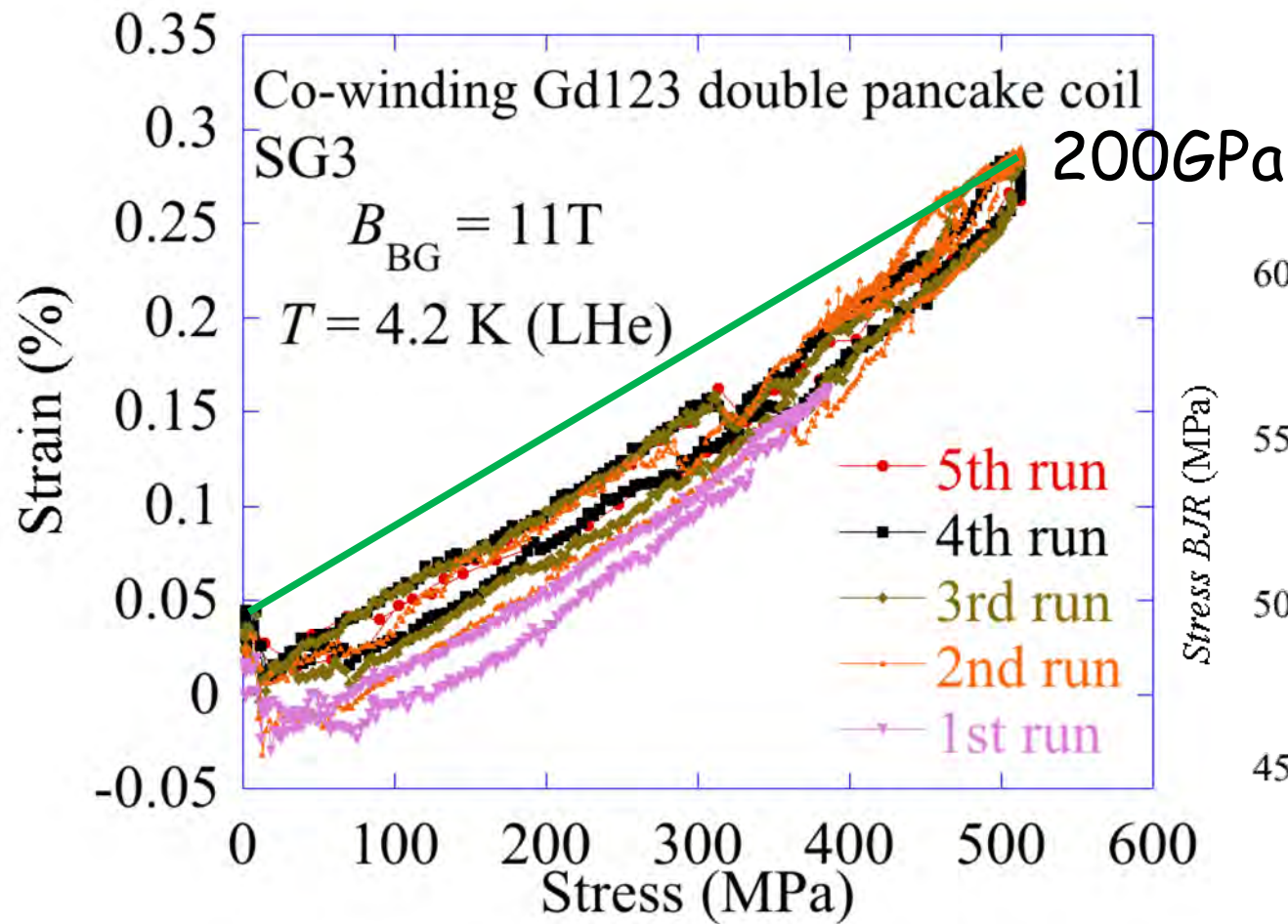
$\phi 360\text{mm}$ -12T SM@HFLSM

# Deformation of coil by hoop stress



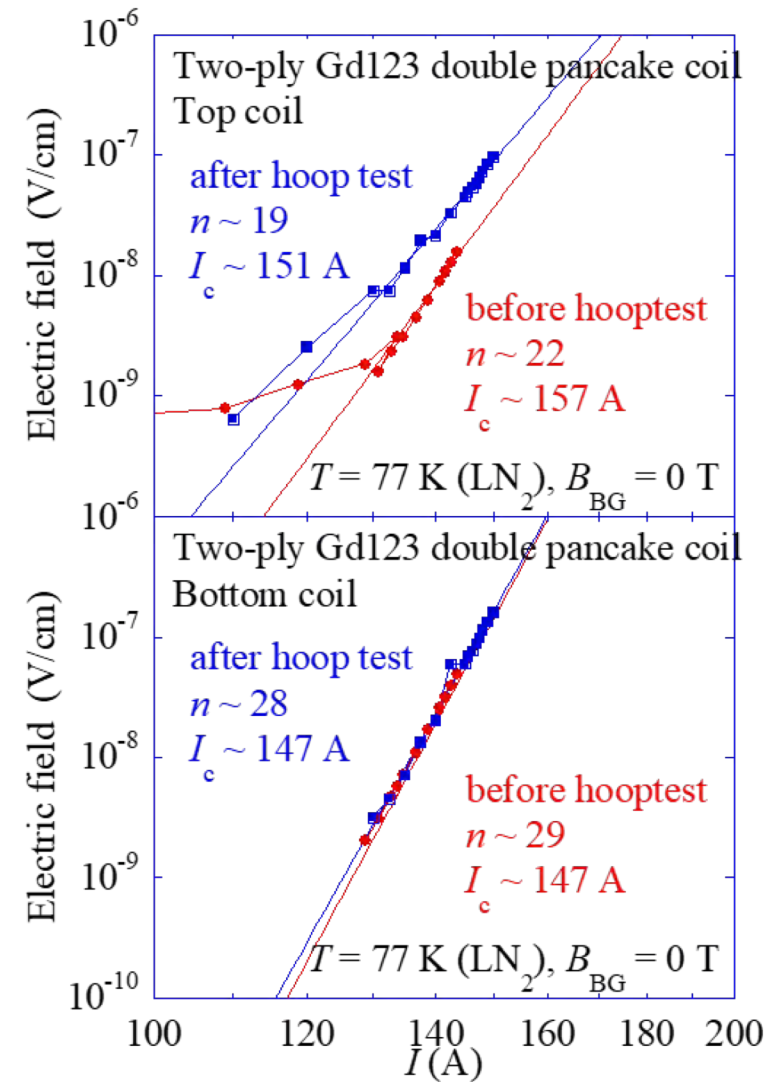
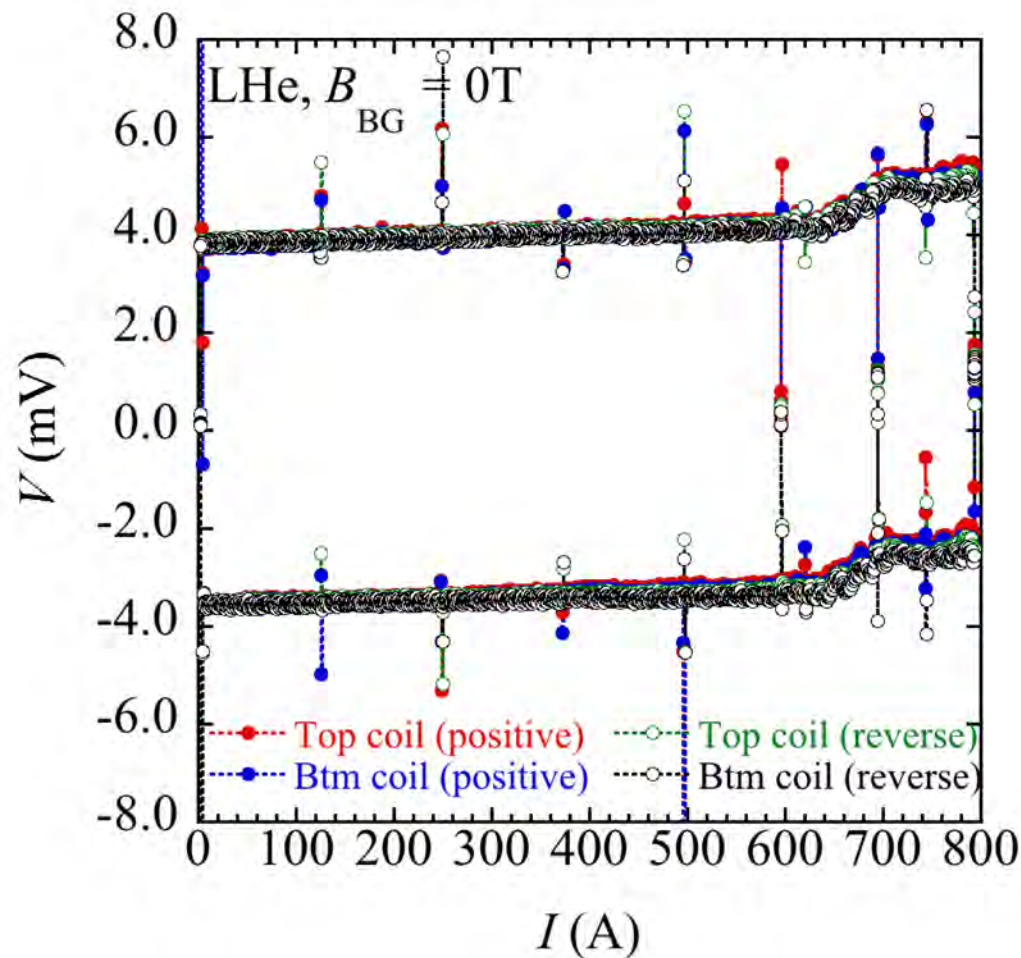


# Deformation of coil



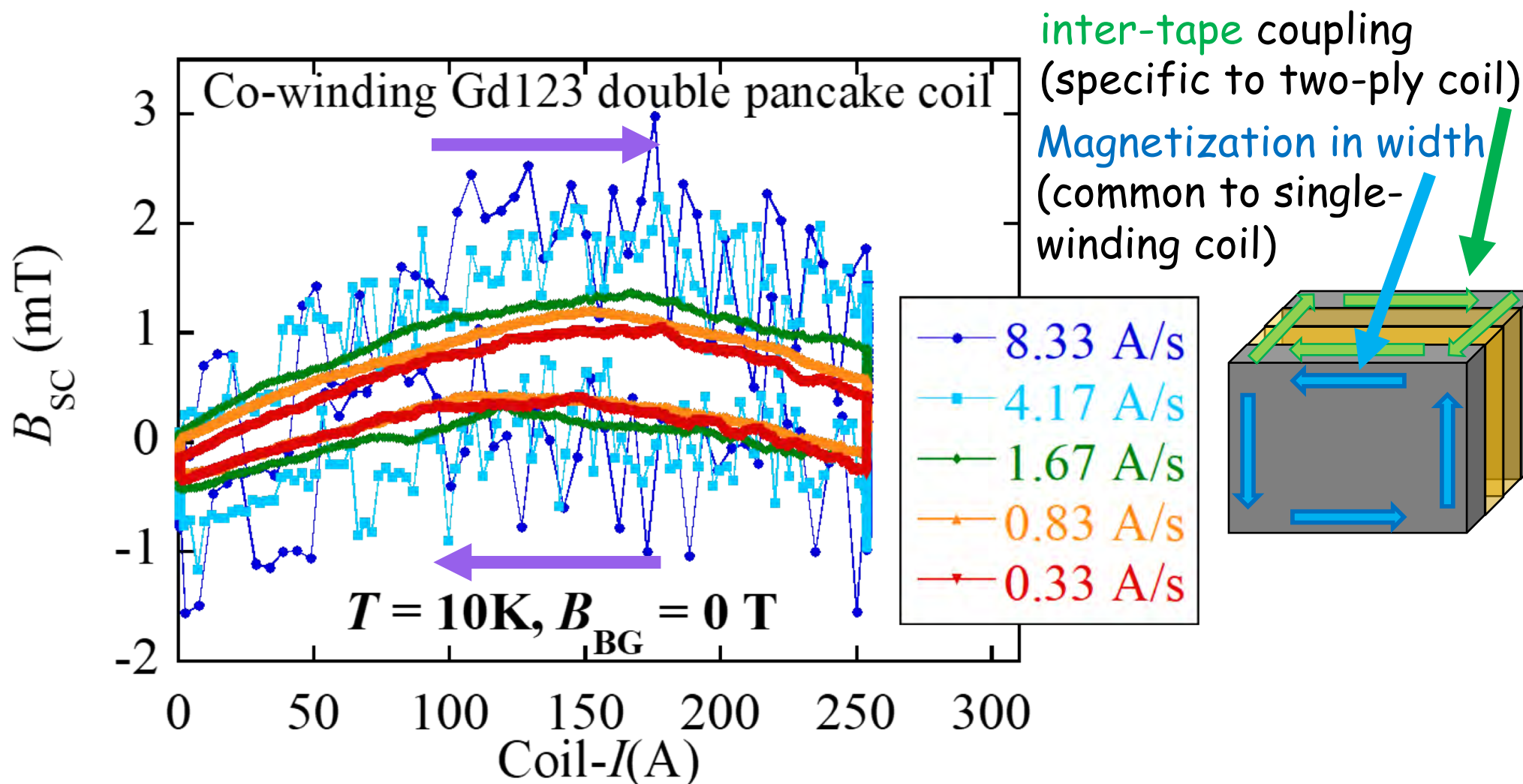
- ✓ The strain of the coil was about 2.5% at 500MPa.
- ✓ The maximum hoop stress; 540 MPa was applied by  $I_{op} = 700\text{ A}$  at 4.2 K and 11 T.
- ✓ The young modulus of coil is  $E = 200\text{-}220\text{ GPa}$ , which is slightly higher than tape.

# Transport properties



- ✓ Inductive voltage  $\approx 4$  mV for 1 A/s ( $L = 0.39$  H)
- ✓ Slight decrease of voltage can be seen. It is probably not ohmic resistance.
- ✓ Top coil was slightly deteriorated. But the degradation is not serious (due to current share?)

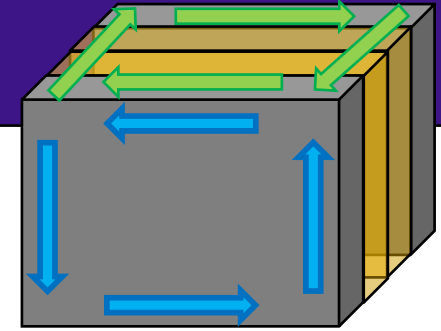
# Shielding current induced field $B_{sc}$



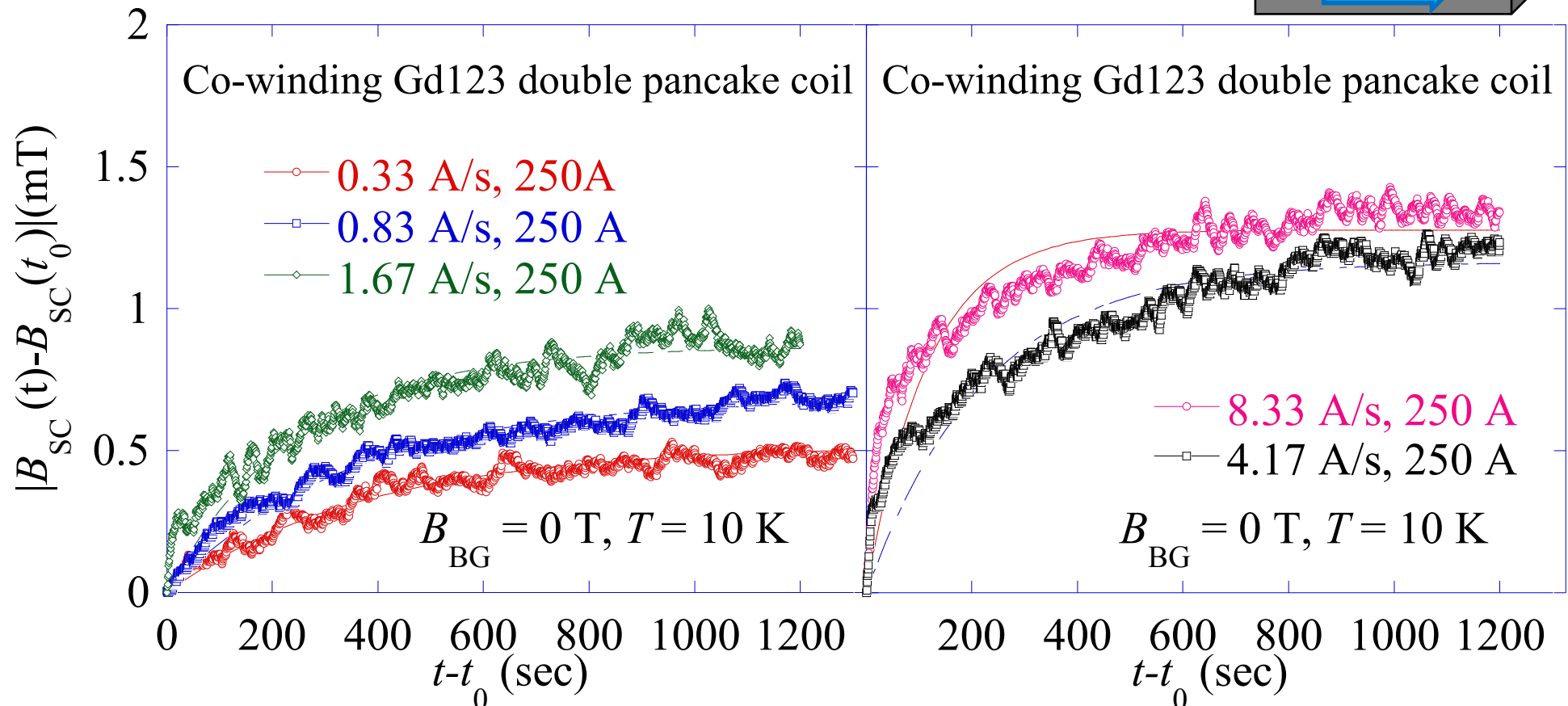
- ✓ Hysteresis of  $B_{sc}$  is opposite to that for single tape wound coil.  
→ The coupling of two Gd123 tapes are dominant for  $B_{sc}$ .
- ✓ The hysteresis width of  $B_{sc}$  increases with increasing ramp rate.



# Relaxation of $B_{sc}$



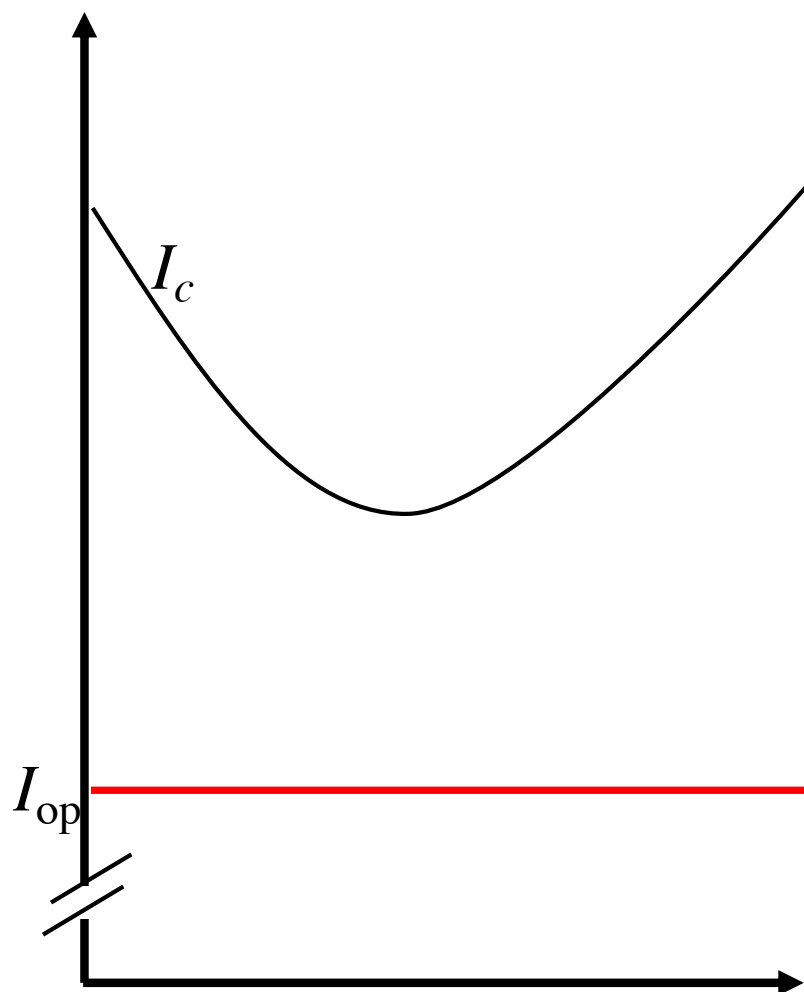
$$|B_{sc}(t) - B_{sc}(t_0)| = \delta B \left[ 1 - \exp\left(-\frac{t - t_0}{\tau}\right) \right]$$



- ✓ Relaxation of  $B_{sc}$  can be fitted well for slow ramp rate but cannot for fast ramp rate. → Different contributions should be considered like inter-coupling and magnetization in tape width.  
Further study is needed.

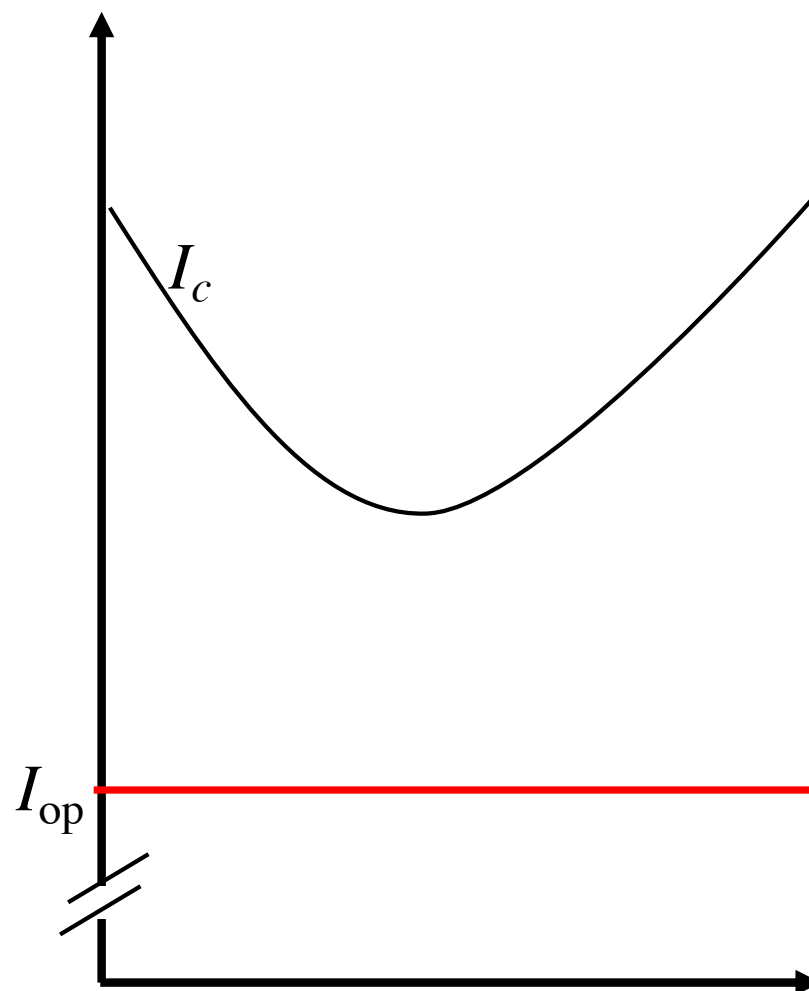
# Quench protection for REBCO w/o local degradation

Passive protection (HFLSM)



Energy is dissipated in damp resistor.

Active protection (NHMFL)

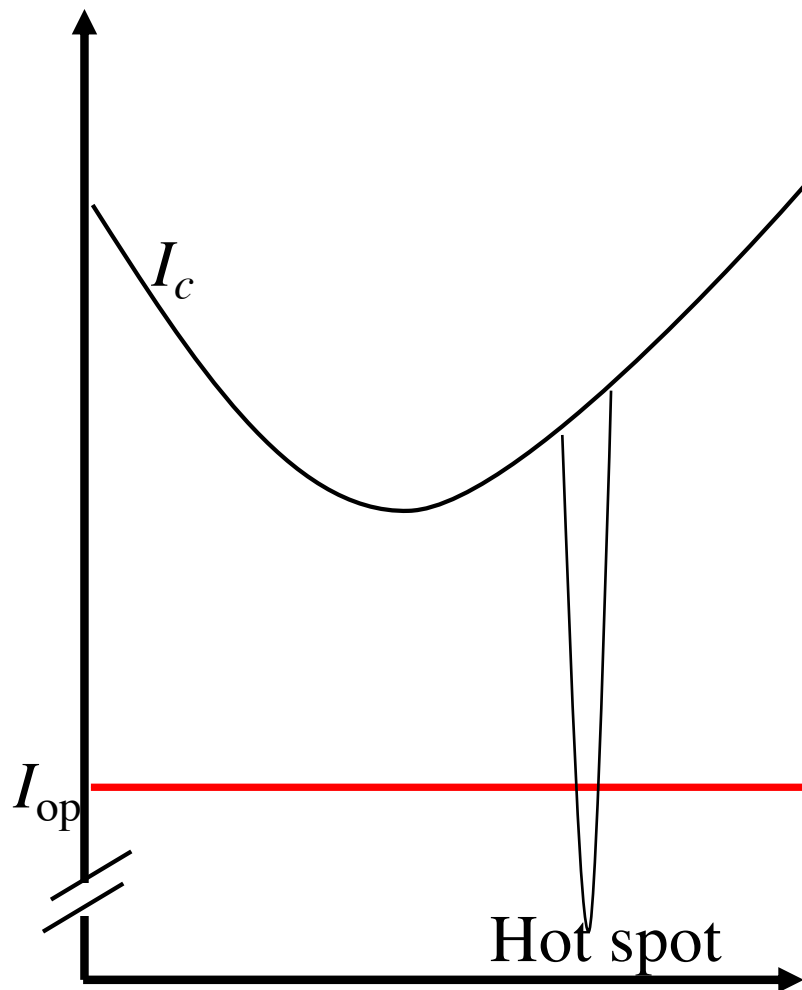


Energy is dissipated in whole coil and resistor.

# Quench protection for REBCO w/ local degradation

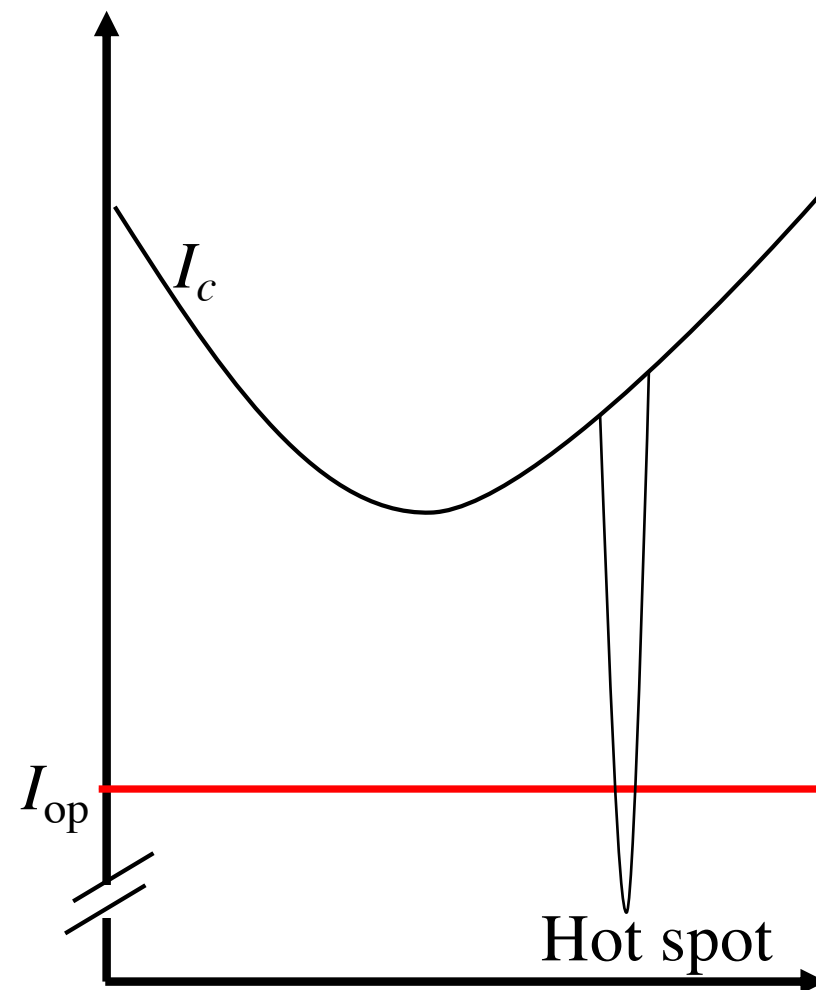
20

Passive protection (HFLSM)



Most energy is dissipated in hot spot

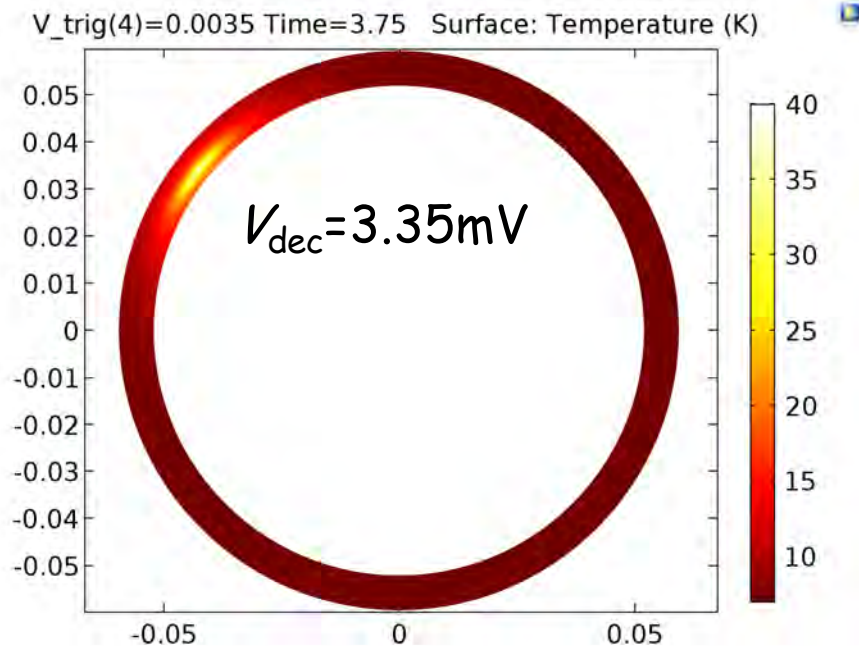
Active protection (NHMFL)



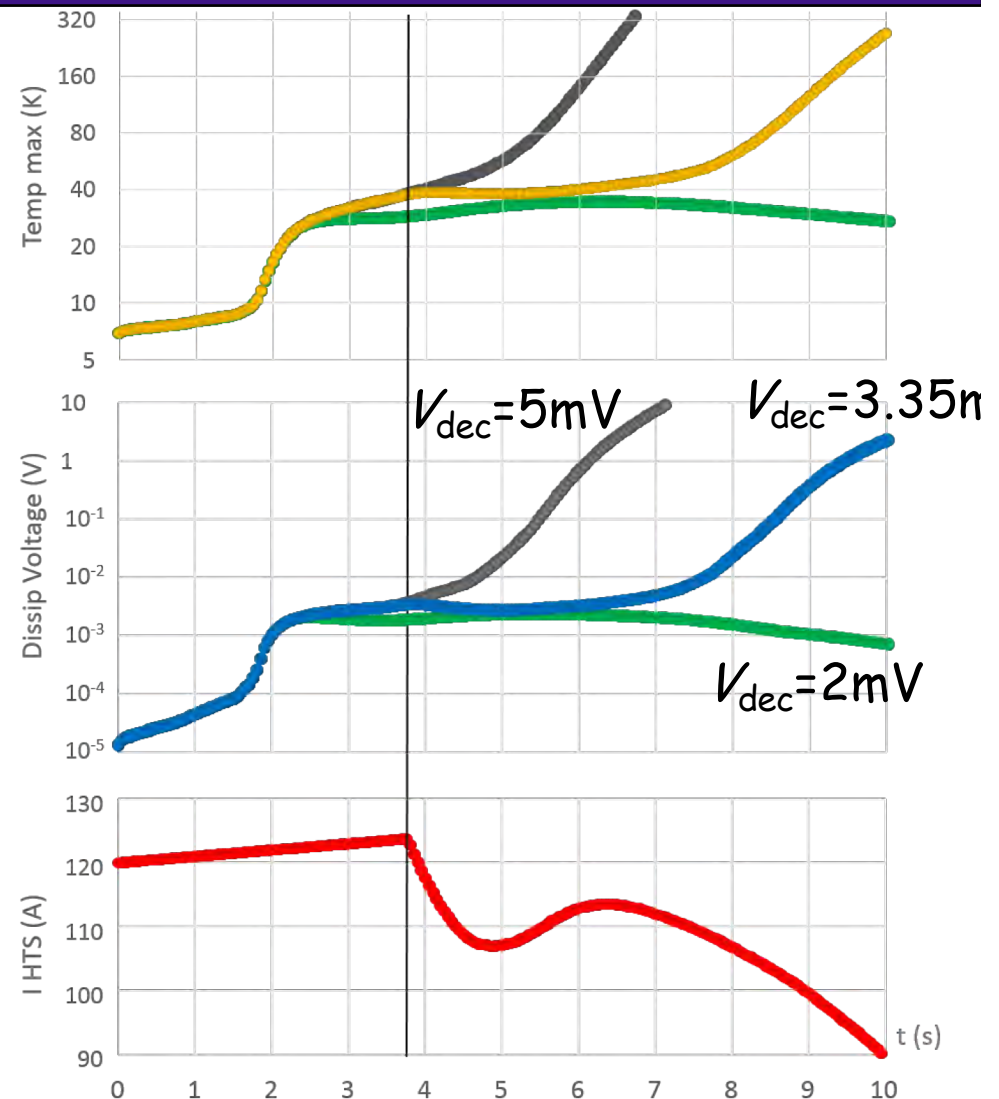
Energy is dissipated in whole coil and resistor.



# Simulation of HTS Insert quench in 25T-CSM



- Upper pancake 40 inner turns, modelled using COMSOL FEM turns discretized in around 2000 5mm-long blocks
- Both tape (130  $\mu\text{m}$ ) and Isolation layers (55  $\mu\text{m}$ ) modelled
- Nominal Critical current with randomized  $\pm 15\%$  distribution
- Lift factor variation with temperature, field and orientation
- 1 damaged block (22 % of nominal value)
- Input : current variation after threshold detection



# Summary

Thank you !

- ✓ Upgrading project of 25T-CSM to 30T is on going. In addition, the design work of CSM beyond 30T is just started.
- ✓ For an achievement of 30T by upgrading of 25T-CSM, we performed test of **twoply Gd123 double pancake coils** under hoop stress.
- ✓ The stable operation of two-ply Gd123 double pancake coil in high stress states up to 540 MPa.
- ✓ The multiple tape winding (similar to PI technique) may be effective to **improve the reliability of Gd123 coil**.
- ✓ The inter-tape coupling of two Gd123 tapes is dominant in screening current induced field and maybe ac-losses.
- ✓ The passive protection is possible if we detect adequate voltage (above a few mV).